



PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Blaine J. Thurgood

Serial No.: 10/685,312

Filed: October 14, 2003

For: INTERPOSER SUBSTRATES WITH
MULTISEGMENT INTERCONNECT
SLOTS, SEMICONDUCTOR, DIE
PACKAGES INCLUDING SAME,
SEMICONDUCTOR DICE FOR USE
THEREWITH AND METHODS OF
FABRICATION

Confirmation No.: Unknown

Examiner: Unknown

Group Art Unit: Unknown

Attorney Docket No.: 2269-5520.1US

CERTIFICATE OF MAILING

I hereby certify that this correspondence along with any attachments referred to or identified as being attached or enclosed is being deposited with the United States Postal Service as First Class Mail on the date of deposit shown below with sufficient postage and in an envelope addressed to the Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

January 8, 2004
Date

Signature

Leah J. Barrow
Name (Type/Print)

PRELIMINARY AMENDMENT

Mail Stop Non-Fee Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, Virginia 22313-1450

Sir:

Prior to examination of the above-referenced patent application on the merits, entry of the amendments as set forth herein is respectfully solicited.

Amendments to the Specification begin on page 2 of this paper.

Amendments to the Claims are reflected in the listing which begins on page 4 of this paper.

Remarks begin on page 7 of this paper.